

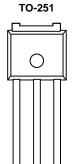
# 30N06-VB TO251 Datasheet N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY					
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)		
60	$0.032 \text{ at V}_{GS} = 10 \text{ V}$	35 <sup>d</sup>	21.7		
60	$0.037 \text{ at V}_{GS} = 4.5 \text{ V}$	30 <sup>d</sup>	21.7		

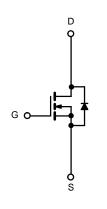
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC





D Top View



N-Channel MOSFET

#### **APPLICATIONS**

- Power Supply
  - Secondary Synchronous Rectification
- DC/DC Converter

ABSOLUTE MAXIMUM RATINGS T <sub>C</sub> = 25 °C, unless otherwise noted						
Parameter		Symbol	Limit	Unit		
Drain-Source Voltage		V <sub>DS</sub>	60	V		
Gate-Source Voltage	V <sub>GS</sub>	± 20	ľ			
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I <sub>D</sub>	35 <sup>d</sup>	Α		
Goriandous Brain Gurient (1) = 130 O)	T <sub>C</sub> = 70 °C	טי	30 <sup>d</sup>			
Pulsed Drain Current	I <sub>DM</sub>	100	^			
Avalanche Current		I <sub>AS</sub>	40			
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	80	mJ		
Manifesture Danier Disable etion d	T <sub>C</sub> = 25 °C	P <sub>D</sub>	59.5 <sup>b</sup>	- W		
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	- FD	2.7			
Operating Junction and Storage Temperature Ra	nge	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	46	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	2.1	C/VV		

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.c. When mounted on 1" square PCB (FR-4 material).
- d. Package limited.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{DS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	60		V	
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.0		3.5	V
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 250	nA
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V			1	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C			50	μΑ
		V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 150 °C			250	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α
Drain Course On State Resistance	Б	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12 A		0.032		Ω
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 10 A		0.037		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A		110		S
Dynamic <sup>b</sup>						
Input Capacitance	C <sub>iss</sub>			1100		pF
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 30 V, f = 1 MHz		281		
Reverse Transfer Capacitance	C <sub>rss</sub>			130		
Total Cata Channel	$Q_g$	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 10 A		46		nC
Total Gate Charge <sup>c</sup>				28		
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		7		
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			6.7		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	2	4	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	16	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V}, R_{L} = 1.5 \Omega$		9	18	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		35	53	ns
Fall Time <sup>c</sup>	t <sub>f</sub>			9	18	
Drain-Source Body Diode Ratings ar	nd Characteris	stics T <sub>C</sub> = 25 °C <sup>b</sup>				
Continuous Current	I <sub>S</sub>				50	^
Pulsed Current	I <sub>SM</sub>				100	Α
Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V		0.75	1.5	V
Reverse Recovery Time	t <sub>rr</sub>			34	51	ns
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	$I_F = 10 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$		2	3	Α
Reverse Recovery Charge	Q <sub>rr</sub>			34	51	nC

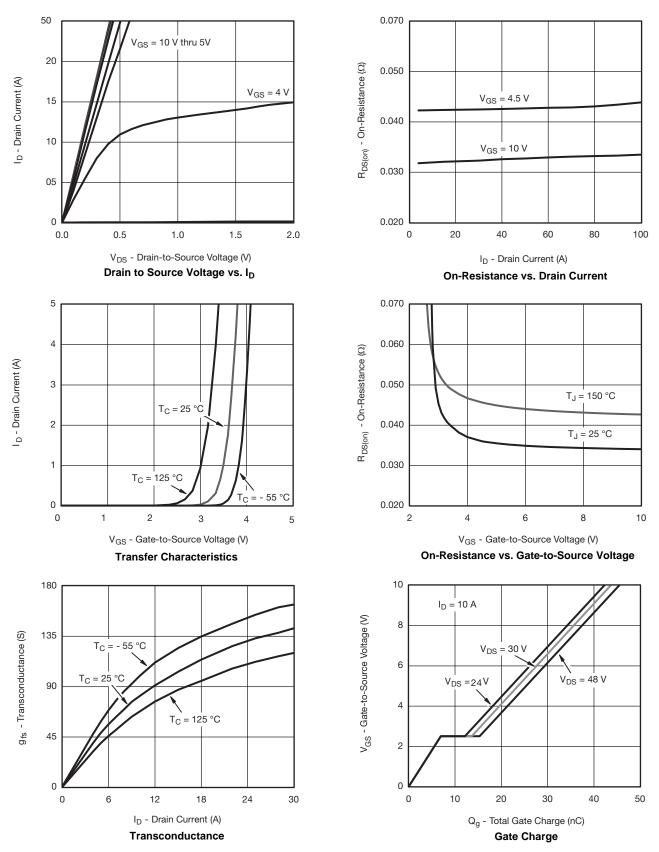
#### Notes:

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %.
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

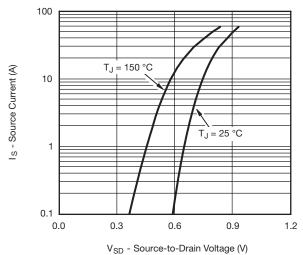


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

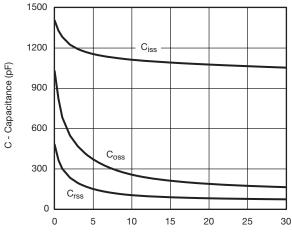




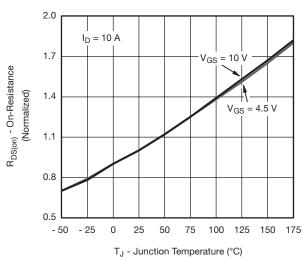
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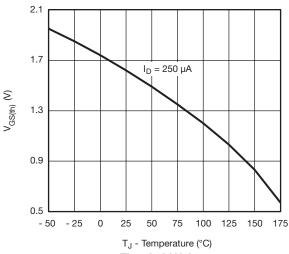
Source-Drain Diode Forward Voltage



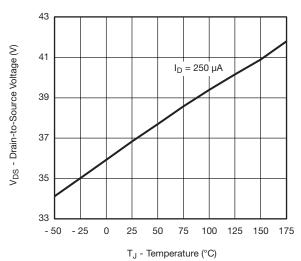
 $V_{DS}$  - Drain-to-Source Voltage (V) **Capacitance** 



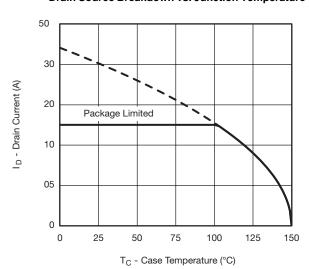
On-Resistance vs. Junction Temperature



Threshold Voltage



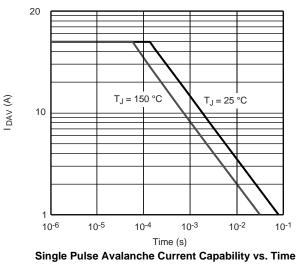
**Drain Source Breakdown vs. Junction Temperature** 

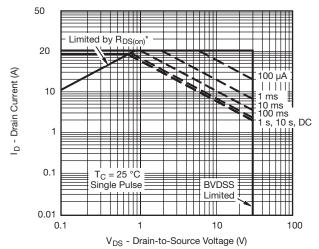


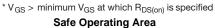
**Current Derating** 

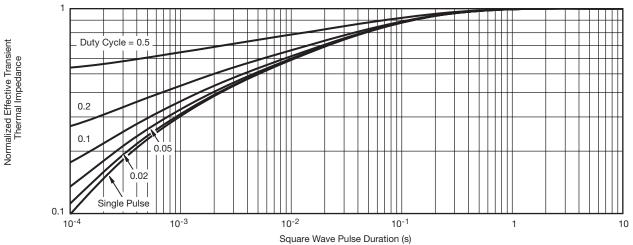


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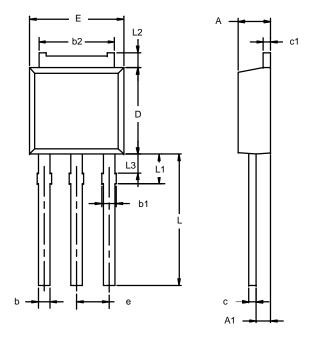
Normalized Thermal Transient Impedance, Junction-to-Case

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# TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

	MILLIM	IETERS	INC	HES		
Dim	Min	Max	Min	Max		
Α	2.21	2.38	0.087	0.094		
A1	0.89	1.14	0.035	0.045		
b	0.71	0.89	0.028	0.035		
b1	0.76	1.14	0.030	0.045		
b2	5.23	5.43	0.206	0.214		
С	0.46	0.58	0.018	0.023		
с1	0.46	0.58	0.018	0.023		
D	5.97	6.22	0.235	0.245		
Ε	6.48	6.73	0.255	0.265		
е	2.28	2.28 BSC 0.090 BSC		2.28 BSC 0.090 BSC		BSC
L	8.89	9.53	0.350	0.375		
L1	1.91	2.28	0.075	0.090		
L2	0.89	1.27	0.035	0.050		
L3	1.15	1.52	0.045	0.060		
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346						

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